

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIUN SUK CHAE	01/31/2019
RECEIVING PARTY DATA	
Name:	THE CATHOLIC UNIVERSITY OF KOREA INDUSTRY-ACADEMIC COOPERATION FOUNDATION
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State/Country:	KOREA, REPUBLIC OF
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16080802
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ATTORNEY DOCKET NUMBER:	9665-42
NAME OF SUBMITTER:	MARK D. PASSLER
SIGNATURE:	/Mark D. Passler/
DATE SIGNED:	02/28/2019
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, I, Hiun Suk Chae, having an address of 24, Huiujeong-ro 1-gil, Mapo-gu, Seoul 04028, Republic of Korea, have made certain inventions which are described in U.S. Patent Application No. 16/080,802 entitled CACULUS REMOVING DEVICE filed on August 29, 2018, and

WHEREAS, The Catholic University of Korea Industry-Academic Cooperation Foundation (hereinafter referred to as Assignee), having a place of business at Songeui Medical Campus, The Catholic University of Korea, 222, Banpo-daero, Seocho-gu, Seoul 06591, Republic of Korea, is desirous of acquiring the entire interest in said inventions throughout the United States of America and the territories thereof,

NOW, THEREFORE, for and in consideration of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, receipt whereof is hereby acknowledged, I hereby sell, assign and transfer unto Assignee, its successors and assigns, the entire right, title and interest throughout the United States of America and the territories thereof in and to said inventions, the aforesaid application, all other applications hereafter filed in the United States, based in whole or in part on said inventions, and all Letters Patents granted upon said applications by the United States, and I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to Assignee. I further grant to Assignee, its successors and assigns, the right to claim for any of said applications the full benefits and priority rights of any international agreement between the United States and any foreign country or countries.

I hereby warrant that I have the full right to make the conveyance herein, and I hereby covenant that me, my heirs, legal representatives and assigns, will when requested, communicate to Assignee, its representatives, successors and assigns, all facts known respecting said inventions, execute all divisional, continuing, reissue, reexamination and foreign or international applications, together with individual assignments therefor, make all rightful oaths, sign all lawful papers, testify in any legal proceeding and generally do everything possible to aid Assignee, its successors and assigns, in the obtaining of Letters Patent.

IN TESTIMONY WHEREOF, this Assignment is executed by the Assignor on the date indicated below.

Date:

31/Jan/2019


Hiun Suk Chae

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